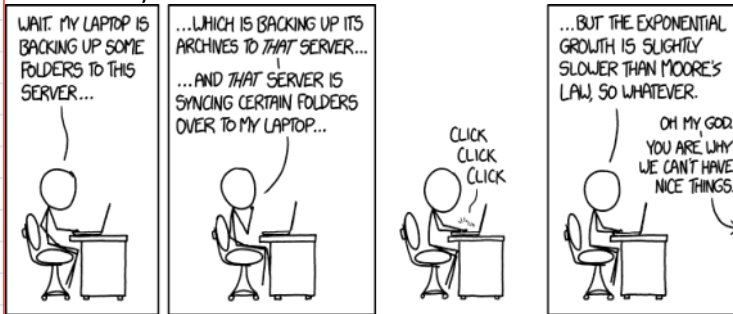


Lecture 2: Technology

Thursday, January 11, 2018 3:35 PM

Outline

- History
- Moore's Law & Dennard Scaling
- Energy/Power of CMOS devices
- Technology trends
 - Transistor
 - Integration
- Latency vs bandwidth

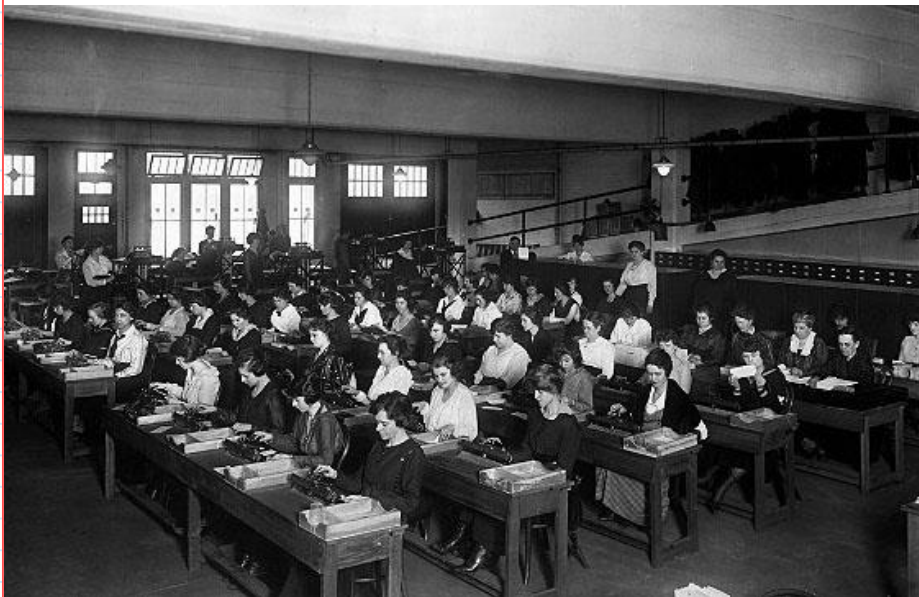


Announcements

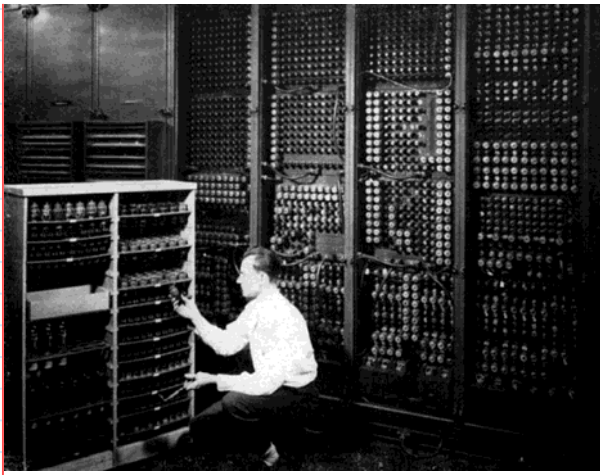
Lab 1 on github
- Minor update for grading
HW 1

History

What did the first computers look like?



Technological change: Electronic computers

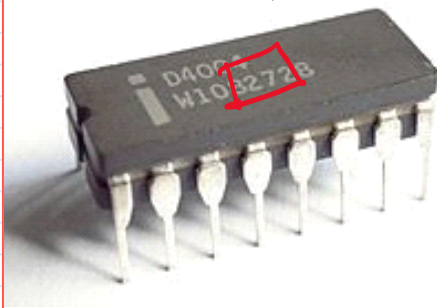


ENIAC: Vacuum tubes

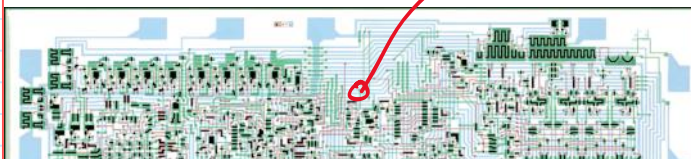


TRADIC: Transistors

Intel 4004



Transistors?



transistor
~ 10 μm

Intel 4004

1 billion

1000

4004

Valuum tubes $\rightarrow \sim 1000 \text{ ft}^3$

transistors $\rightarrow 10 \text{ ft}^3$
100
1000

3 ft^3

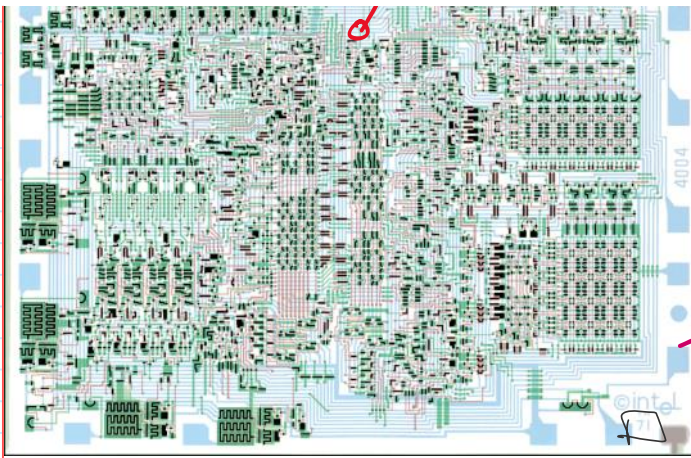
Power

ENIAC $\rightarrow 160 \text{ kW}$

$\rightarrow 100 \text{ W}$

CMOS transistors



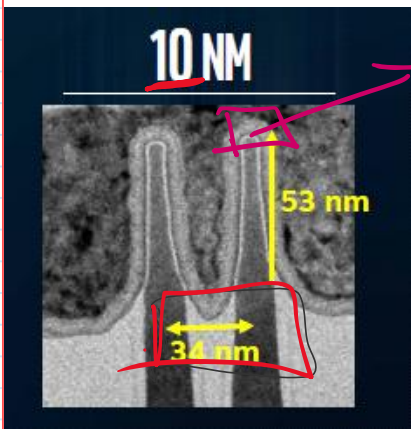


1000

4004

2300 transistors

Today



Printing resolution

↑ up

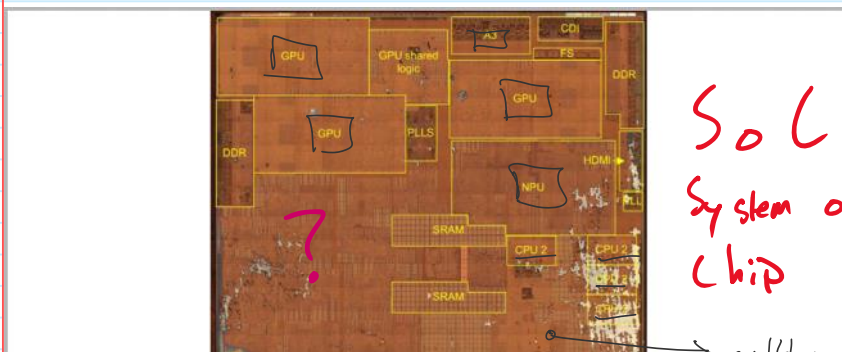
light \rightarrow 180 nm
20 nm



AMD Threadripper Transistors?

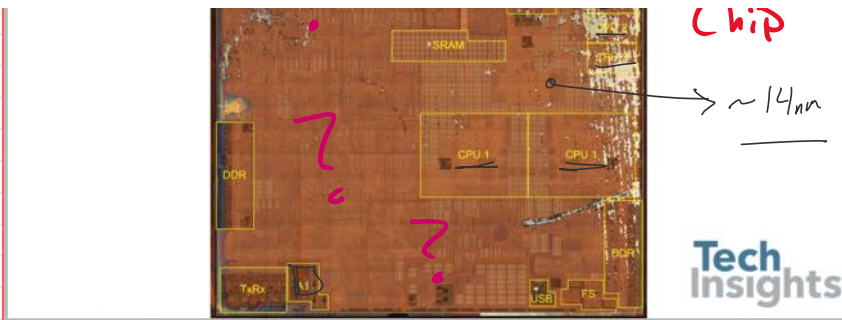
10 billion
1 trillion

100 million
100,000



SoC
System on a chip

~ 14 nm



Apple A11 in the iPhone 8 & X Transistors?

4.3 billion

Moore's Law

Cramming More Components onto Integrated Circuits '68

GORDON E. MOORE, LIFE FELLOW, IEEE

With unit cost falling as the number of components per circuit rises, by 1975 economics may dictate squeezing as many as 65,000 components on a single silicon chip.

The future of integrated electronics is the future of electronics itself. The advantages of integration will bring about a proliferation of electronics, pushing this science into many new areas.

Integrated circuits will lead to such wonders as home computers—or at least terminals connected to a central computer—automatic controls for automobiles, and personal portable communications equipment. The electronic wristwatch needs only a display to be feasible today.

But the biggest potential lies in the production of large systems. In telephone communications, integrated circuits

Each approach evolved rapidly and converged so that each borrowed techniques from another. Many researchers believe the way of the future to be a combination of the various approaches.

The advocates of semiconductor integrated circuitry are already using the improved characteristics of thin-film resistors by applying such films directly to an active semiconductor substrate. Those advocating a technology based upon films are developing sophisticated techniques for the attachment of active semiconductor devices to the passive film arrays.

Both approaches have worked well and are being used in equipment today.

an observation not a law
↳ economics

What is Moore's Law?

Technology growing exponentially
Double speed every 18 months

Double transistors per area every 12 mo.

↳ 18
24

Driver behind Moore's Law: Dennard Scaling

Table 1
Scaling Results for Circuit Performance

Device or Circuit Parameter	Scaling Factor
Device dimension t_{ox}, L, W	$1/\kappa$
Doping concentration N_a	κ
Voltage V	$1/\kappa$
Current I	$1/\kappa$
Capacitance $C/A/t$	$1/\kappa$
Delay time/circuit VC/I	$1/\kappa$
Power dissipation/circuit VI	$1/\kappa^2$
Power density VI/A	1

reduce transistor size

" " power

increase speed

$\sqrt{2}$

implication \rightarrow same unit area
double transistors
go faster
use the same power

Energy and power of CMOS

How does power and energy relate?

Power

Energy

Energy and power of CMOS

How does power and energy relate?

Energy = $P \cdot t$
 = static + dynamic

Static energy: ~~smaller~~ transistors
 more leakage

Dynamic energy:

$E = C V^2 \rightarrow$ Voltage
 \hookrightarrow capacitance \rightarrow how many transistors

Power =

$\rightarrow P = \frac{1}{2} C V^2 \cdot f \rightarrow$ frequency

What is the most effective way to reduce (dynamic) power?

low voltage has biggest effect on power

Power

consuming our time

Cool

power input

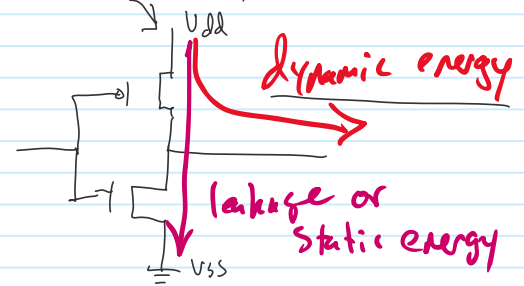
Energy

cost

carbon footprint

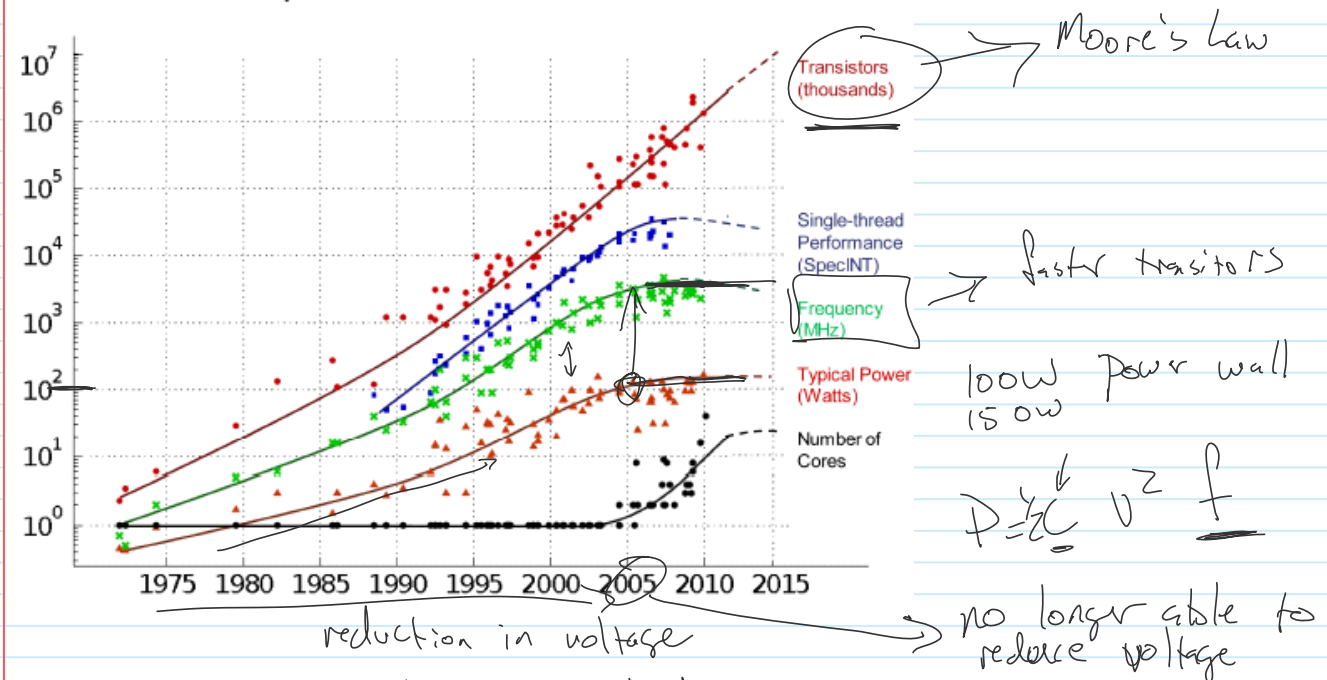
finite

Battery



Trends

35 Years of Microprocessor Trend Data



"solution" \rightarrow multicore \rightarrow hard to program

or

\rightarrow specialization

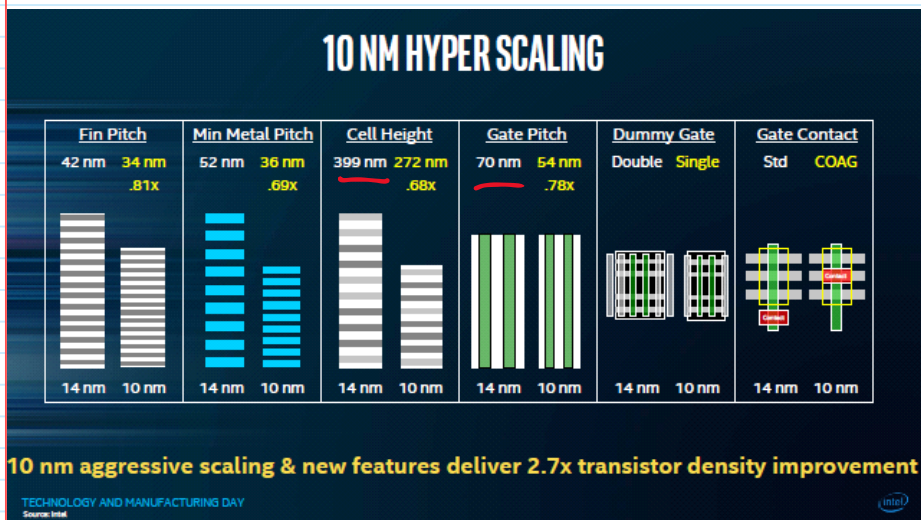
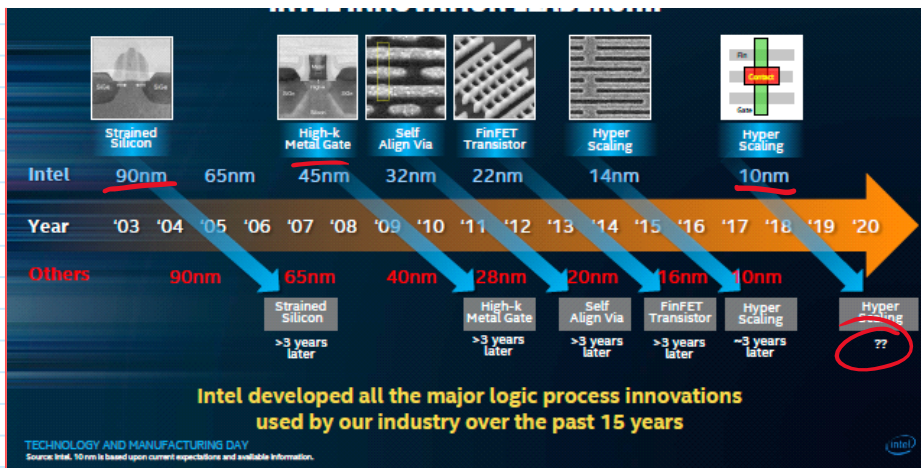
\rightarrow Dark Silicon \rightarrow Dim Silicon

Slides from Intel



Chips are manufactured
 at a fabrication plant
 or Fab

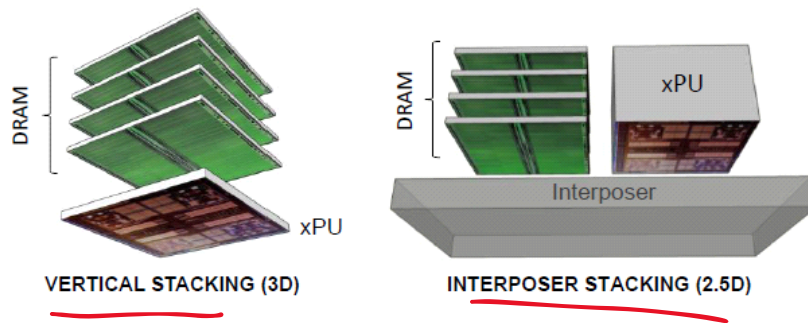
5 ish



DIE STACKING IS IDEAL FOR INTEGRATION

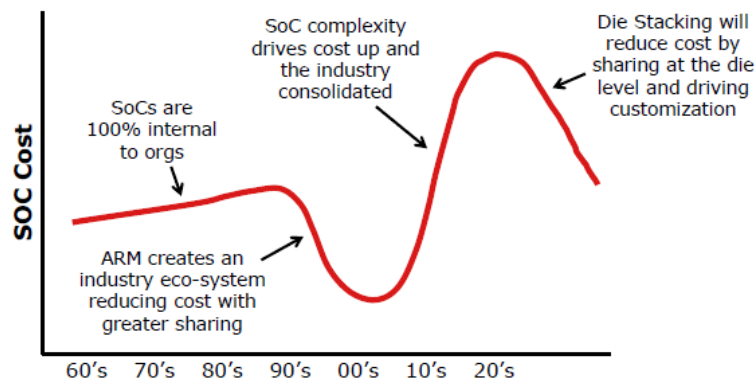


- All they do is reduce metal interconnect by improving proximity of disparate technologies

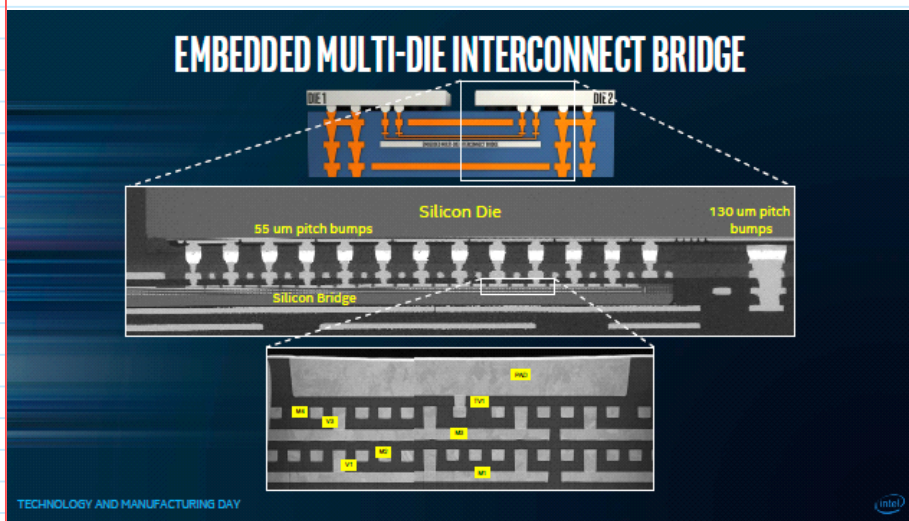


40 | DIE STACKING IS HAPPENING! | DECEMBER 9, 2013

AS ALWAYS COST WILL DRIVE THE NEXT EVOLUTION OF SOCS



50 | DIE STACKING IS HAPPENING! | DECEMBER 9, 2013



Latency vs bandwidth: Moving data around

[Grace Hopper - Nanoseconds](#)

SeHouMusic



<https://youtu.be/JEpsKnWZrJ8>

Trends

Bandwidth:

Latency:

Little's Law: